MPQ5071



5.5V, 0.5A, Low R_{DS(ON)} Load Switch with Programmable Current Limit, AEC-Q100 Qualified

DESCRIPTION

The MPQ5071 is a programmable load switch that provides 0.5A of load protection across a 0.5V to 5.5V voltage range. With low $R_{DS(ON)}$ in a tiny package, the MPQ5071 provides a highly efficient, space-saving solution for notebooks, tablets, and other portable device applications.

The MPQ5071's soft start (SS) function avoids inrush current during circuit start-up. The MPQ5071 also provides a programmable softstart time, output discharge functions, overcurrent protection (OCP), and thermal shutdown.

The maximum load at the output source is current-limited, which is accomplished utilizing a sense MOSET topology.

The magnitude of the current limit is controlled by an external resistor from the ILIM pin to ground (GND).

An internal charge pump drives the power device gate, allowing a low on resistance DMOS power MOSET of just $50m\Omega$.

The MPQ5071 is available in a tiny, spacesaving QFN-12 (2mmx2mm) package.

FEATURES

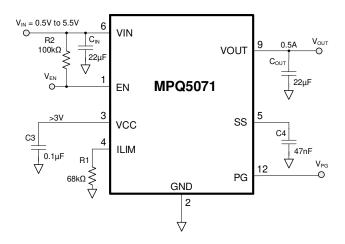
- Guaranteed Industrial/Automotive
 Temperature Range Limits
- 0.5V to 5.5V V_{IN} Range
- Shutdown Current <5µA
- Integrated 50mΩ Low R_{DS(ON)} MOSETs
- 0.5A Load Current
- Push/Pull Power Good (PG) Indicator
- Adjustable Start-Up Slew Rate
- Output Discharge
- Short-Circuit Protection (SCP) <200ns
- Thermal Shutdown Protection
- Available in a Space-Saving QFN-12 (2mmx2mm) Package
- Available in AEC-Q100 Grade 1

APPLICATIONS

- Notebook and Tablet Computers
- Portable Devices
- Solid State Drives (SSDs)
- Handheld Devices

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TYPICAL APPLICATION





ORDERING INFORMATION

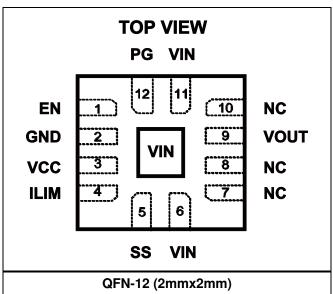
Part Number*	Package	Top Marking	MSL Rating	
MPQ5071GG	QFN-12 (2mmx2mm)	See Below	1	
MPQ5071GG-AEC1		See Below	I	

* For Tape & Reel, add suffix -Z (e.g. MPQ5071GG-AEC1-Z).

TOP MARKING

LQY

LQ: Product code of MPQ5071GG & MPQ5071GG-AEC1 Y: Year code LLLL: Lot number



PACKAGE REFERENCE



Pin #	Name	Description
1	EN	Enable input. Pull EN below the specified threshold to shut down the chip.
2	GND	Ground.
3	VCC	Supply voltage to the control circuitry.
4	ILIM	Output current limit configuration. Place a resistor to GND to set the overload current limit level.
5	SS	Soft start. An external capacitor connected to the SS pin sets the slew rate for the output voltage soft-start period.
6, 11, exposed pad	VIN	Input power supply.
9	VOUT	Output to the load.
12	PG	Power good. Push/pull output.
7, 8, 10	NC	Not connected. It is recommended to connect this pin to VOUT to improve thermal performance.

PIN FUNCTIONS

ABSOLUTE MAXIMUM RATINGS (1)

V _{IN}	0.3V to +6.5V
V _{CC}	0.3V to +6.5V
V _{OUT}	0.3V to +6.5V
EN, SS, ILIM(0.3V to V_{CC} +0.3 V
Junction temperature	150°C
Lead temperature	260°C
Continuous power dissipation	(2)
QFN-12 (2mmx2mm)	1.6W

ESD Ratings

Human body model (HBM)	±2kV
Charged device model (CDM)	±750V

Recommended Operating Conditions ⁽³⁾

Supply voltage (V _{IN})	0.5V to 5.5V
Supply voltage (V _{CC})	
Output voltage (V _{OUT})	0.5V to 5.5V
Operating junction temp (T _J).	40°C to +125°C

Thermal Resistance ⁽⁴⁾ θ_{JA} θ_{JC}

QFN-12 (2mmx2mm)..... 80..... 16... °C/W

Notes:

- 1) Exceeding these ratings may damage the device.
- 2) The maximum allowable power dissipation is a function of the maximum junction temperature T_J (MAX), the junction-toambient thermal resistance θ_{JA} , and the ambient temperature T_A. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P_D (MAX) = (T_J (MAX) - T_A) / θ_{JA} . Exceeding the maximum allowable power dissipation can cause excessive die temperature, and the device may go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- The device is not guaranteed to function outside of its operating conditions.
- 4) Measured on JESD51-7, 4-layer PCB.



ELECTRICAL CHARACTERISTICS

 V_{IN} = 3.6V, V_{CC} = 3.6V, T_J = -40°C to +125°C, typical values are at T_J = 25°C, unless otherwise noted.

Parameters	Symbol	Condition	Min	Тур	Max	Units
Input and Supply Voltage Range						
Input voltage	VIN		0.5		5.5	V
Supply voltage	Vcc		3		5.5	V
Supply Current		·				
Off state is shown summark		$V_{IN} = 5V, EN = 0, T_J = 25^{\circ}C$			1	μA
Off-state leakage current	I _{OFF}	V _{IN} = 5V, EN = 0, -40°C < TJ < +125°C			5	μA
		$V_{CC} = 5V, EN = 0$		0.1	1	
V _{cc} standby current	I _{STBY}	$V_{CC} = 5V$, enable, no load, T _J = 25°C		180	230	μA
		$V_{CC} = 5V$, enable, no load, -40°C < T _J < +125°C		180	250	
Power MOSET			-			
On resistance	Rds(on)			50 50 60	70 80 80	mΩ
		$V_{CC} = 3.3V, -40^{\circ}C < T_{J} < +125^{\circ}C$		60	90	
Thermal Shutdown and Recovery (5)						
Shutdown temperature	T _{STD}			150		°C
Hysteresis	T _{HYS}			30		°C
Under-Voltage Protection		l				
VCC under-voltage lockout (UVLO) threshold	Vcc_uvlo	UVLO rising threshold		2.6	2.95	V
UVLO hysteresis	VUVLO_HYS			200		mV
Soft Start (SS)		1				
SS pull-up current	lss	Fixed slew rate	4	11	17	μA
Enable (EN)						m . 1
EN rising threshold	V _{ENH}		1.3	1.5	1.7	V
EN hysteresis	VEN_HYS			200		mV
ILIM	VEN_HTS			200	l	
Current limit	IOUT	$R_{\text{LIM}} = 24k\Omega$, ramp I_{OUT} records the peak current limit value		1.4		Α
Discharge Resistance				I	1	
Discharge resistance	R _{DIS}			200		Ω
Power Good (PG)		1			1	
PG rising threshold	V _{PG_R}	Voltage gap between V_{OUT} and V_{IN}	140	280	450	mV
PG threshold	VPG_HYS			60		mV
PG delay	tPG_D			50		μs
PG high	VPG_H	V _{CC} = 3.3V	3.2			V
PG low	VPG_L	Sink 1mA			0.3	V

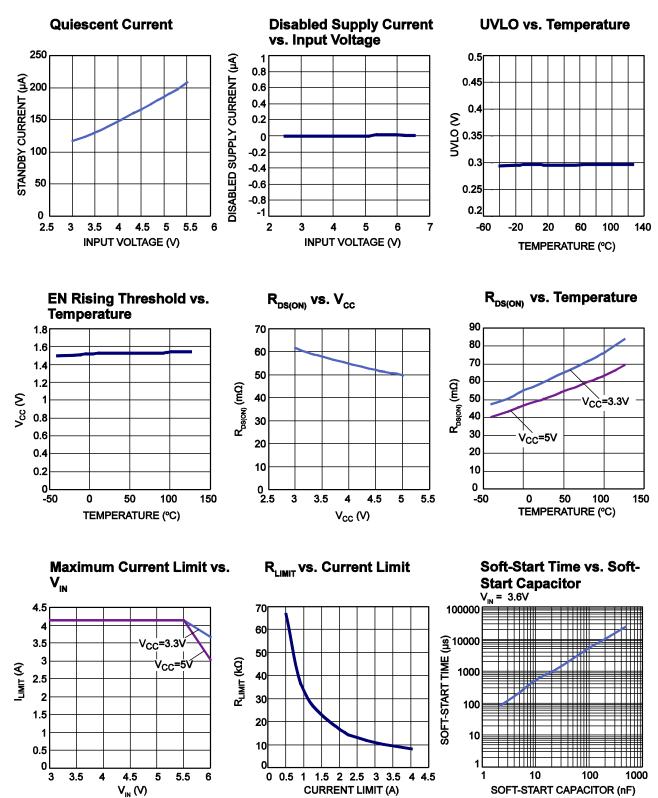
Notes:

5) Guaranteed by design.



TYPICAL PERFORMANCE CHARACTERISTICS

 V_{IN} = 3.6V, V_{CC} = 3.6V, R_{ILIM} = 13k Ω , T_A = 25°C, unless otherwise noted.



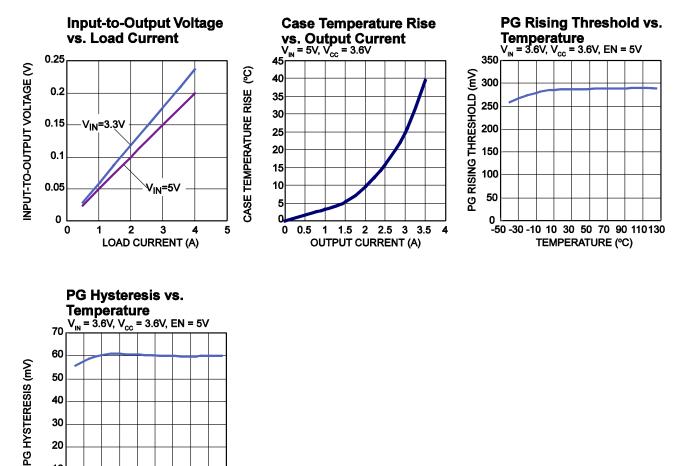


10 0

-50 -30 -10 10 30 50 70 90 110130 TEMPERATURE (°C)

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

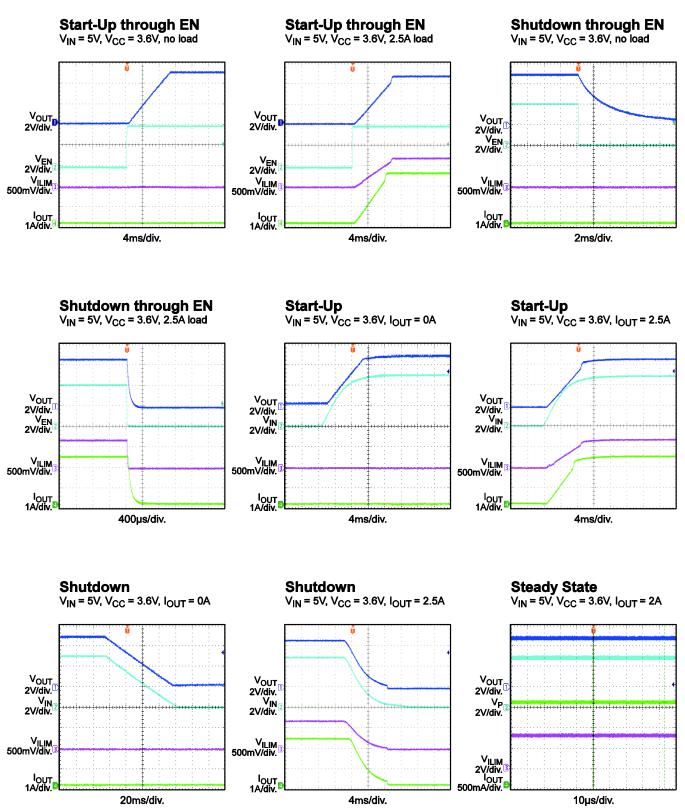
 V_{IN} = 3.6V, V_{CC} = 3.6V, R_{ILIM} = 13k $\Omega,$ T_{A} = 25°C, unless otherwise noted.





TYPICAL PERFORMANCE CHARACTERISTICS (continued)

 V_{IN} = 3.6V, V_{CC} = 3.6V, EN = 4V, R_{ILIM} = 13k Ω , T_A = 25°C, unless otherwise noted.

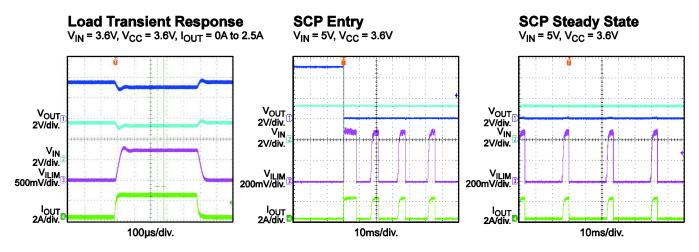


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TYPICAL PERFORMANCE CHARACTERISTICS (continued)

 V_{IN} = 3.6V, V_{CC} = 3.6V, EN = 4V, R_{ILIM} = 13k Ω , T_A = 25°C, unless otherwise noted.



SCP Recovery VIN = 5V, V_{CC} = 3.6V



FUNCTIONAL BLOCK DIAGRAM

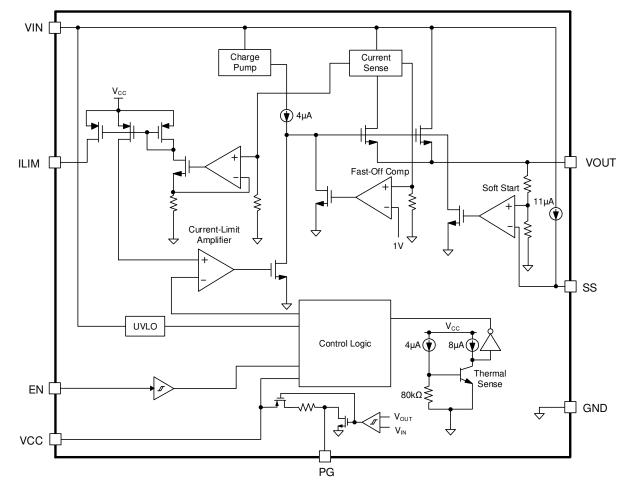


Figure 1: Functional Block Diagram



OPERATION

The MPQ5071 is designed to limit the inrush current to the load when a circuit card is inserted into a live backplane power source, limiting the backplane's voltage drop and the slew rate of the voltage to the load. The MPQ5071 provides an integrated solution that monitors the input voltage, output voltage, and output current — eliminating the need for an external current power MOSFET and a current-sense device.

Enable (EN)

The MPQ5071 is enabled when the input voltage exceeds the under-voltage lockout (UVLO) threshold (typically 0.5V), and the enable (EN) pin is pulled above 1.5V. Pulling the voltage down to ground (GND) disables the MPQ5071.

Current Limit

The MPQ5071 provides a constant current limit programmed by an external resistor. Once the device reaches its current limit threshold, the IC regulates the gate voltage to hold a constant current in the power MOSET. The typical response time is about 20µs. During the response time, a small overshoot in the output current may occur. The preset current limit value can be calculated with Equation (1):

$$I_{\text{LIMIT}} = (1 / R_{\text{ILIM}}) \times S \tag{1}$$

Where S is the current-sense ratio of the MPQ5071, and the typical value is 33000 when $V_{IN} = 3.6V$.

If the current limit block starts regulating the output current, power loss in the power MOSFET causes the IC temperature to rise. If the junction temperature rises too high, the MPQ5071 goes into thermal shutdown. After thermal shutdown, the output is disabled until the over-temperature (OT) fault is removed. The OT threshold is 150°C, and the hysteresis is 30°C.

Power Good (PG)

The power good (PG) pin is the push/pull of a MOSFET that can be pulled high to V_{CC} . The MOSFET turns on when an input voltage is applied that pulls the PG pin to GND. Once the

voltage gap between V_{IN} and V_{OUT} is less than 280mV, the PG pin is pulled high after a 50µs delay. Once the voltage gap is exceeds 340mV, the PG pin is pulled low.

Short-Circuit Protection (SCP)

If a short circuit causes the load current to rapidly increase, the current may exceed its limit threshold. If the current reaches the internal secondary current limit (about 7A), a fast turn-off circuit shuts off the power MOSET, limiting the peak current through the switch and the input voltage drop. The total short circuit response time is about 200ns. If the fast turn-off succeeds, the power MOSET remains off for 80µs. After the 80µs, the power MOSET turns back on. If the short circuit remains, the MPQ5071 reduces and holds the current limit until the part is hot enough to trigger thermal shutdown. Once the short circuit condition is removed. the current limit automatically recovers to the preset value.

Output Discharge

The MPQ5071 has an output discharge function. This function discharges V_{OUT} with an internal pull-down resistor when the IC is disabled and the load is very light.

Soft Start (SS)

The capacitor connected to the SS pin determines the soft-start time. An internal, 11μ A constant-current source charges the SS capacitor and ramps up the voltage on the SS pin. The output voltage rises at five times the slew rate of the SS voltage.

The soft-start time can be calculated with Equation (2):

$$t_{SS}(ms) = \frac{1}{5} \times \frac{V_{OUT}(V) \times C_{SS}(nF)}{I_{SS}(\mu A)}$$
(2)

Where t_{SS} is the soft-start time, I_{SS} is the internal 11µA constant current, and C_{SS} is the external SS capacitor.

The suggested minimum capacitance is no less than 4.7nF. If the SS pin is floating or SS capacitor is too small, the V_{OUT} rise time is limited by the power MOSFET charge time.

APPLICATION INFORMATION

COMPONENT SELECTION

Selecting the ILIM Resistor

The current limit value is set by the ILIM resistor (R_{ILIM}) . The current limit can be calculated with Equation (1) on page 10.

The suggested current limit threshold should be 10% to 20% greater than maximum load current. For example, if a system's full load is 0.5A, set the current limit to 0.55A.

Selecting the ILIM Capacitor

The internal, advanced auto-zero comparator offers high-accuracy current monitoring, though it causes a small amount of jitter on the ILIM pin. To stabilize the ILIM pin, mount a small ceramic capacitor between the ILIM pin and GND. It is recommended to use a capacitor that is less than 1nF.

Selecting the SS Capacitor

An internal, 11μ A constant-current source charges the SS capacitor, which ramps up the voltage on the SS pin. The output voltage follows the SS voltage slew rate.

If the inrush of the output current reaches the current limit during start-up (e.g. if there is a large output capacitor or large load), the MPQ5071 limits the output current, and the soft-start time increases simultaneously (see Figure 2 and Figure 3).

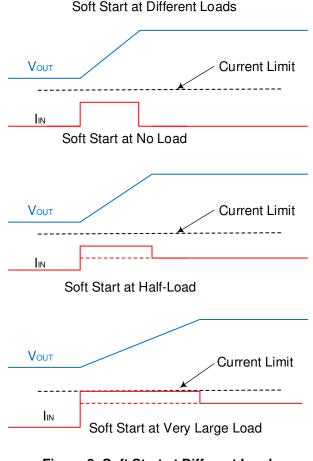
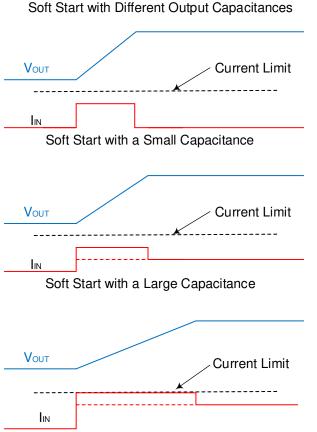


Figure 2: Soft Start at Different Loads





Soft Start with a Very Large Capacitance

Figure 3: Soft Start at Different Output Capacitances

Design Example

Table 1 and Figure 5 provide details for design examples.

Table 1: Components Selection Guide

V _{IN} (V)	3.6	3.6	3.6
Max Load Range (A)	0.5	1	2
R _{LIMIT} (kΩ)	47	27.4	15
SS Capacitance (nF)	22	47	100
SS Time (ms)	1	2.4	5.4

Efficient PCB layout is critical for stable operation. For the best results, refer to Figure 4 and follow the guidelines below:

- 1. Place R_{ILIM} close to the ILIM pin.
- 2. Place the input capacitor close to the VCC pin.
- 3. Place vias around the IC to improve thermal performance.

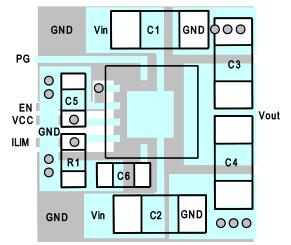


Figure 4: Recommended PCB Layout

PCB Layout Guidelines



TYPICAL APPLICATION CIRCUIT

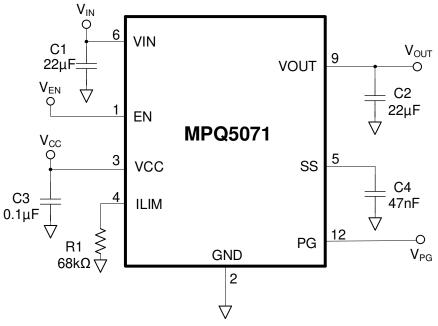
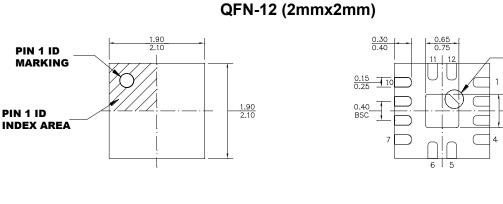


Figure 5: Typical Application Circuit



PACKAGE INFORMATION



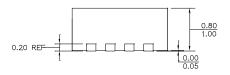
TOP VIEW

BOTTOM VIEW

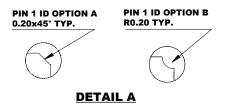
PIN 1 ID

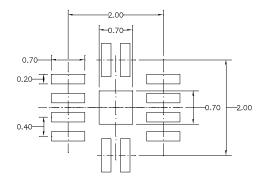
.65 .75

SEE DETAIL A



SIDE VIEW





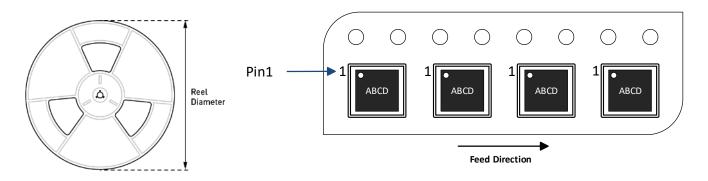
RECOMMENDED LAND PATTERN

NOTE:

1) ALL DIMENSIONS ARE IN MILLIMETERS. 2) EXPOSED PADDLE SIZE DOES NOT INCLUDE MOLD FLASH. 3) LEAD COPLANARITY SHALL BE 0.10 MILLIMETERS MAX. 4) JEDEC REFERENCE IS MO-229. 5) DRAWING IS NOT TO SCALE.



CARRIER INFORMATION



Part Number	Package Description	Quantity /Reel	Quantity /Tube	Quantity /Tray	Reel Diameter	Carrier Tape Width	Carrier Tape Pitch
MPQ5071GG-Z	QFN-12						
MPQ5071GG- AEC1–Z	(2mmx2mm)	5000	N/A	N/A	13in	12mm	8mm



REVISION HISTORY

Revision #	Revision Date	e Description Pages	
1.0	1/11/2021	Initial Release	-

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